

PATENT NUMBER and
ISSUE DATE

U.S. UTILITY Patent Application

APPL. NUM 10086117	FILING DATE 02/26/2002	CLASS 226	SUBCLASS 735	GAU 222	EXAMINER Lewis
**APPLICANTS: Bojkov Christo; Coffman Phillip; Smith Patricia;					
CONTINUING DATA VERIFIED: THIS APPLN CLAIMS BENEFIT OF 60/342,949 12/21/2001					
<h1>BEST AVAILABLE COPY</h1>					
** FOREIGN APPLICATIONS VERIFIED:					
PG-PUB <input type="checkbox"/> DO NOT PUBLISH <input type="checkbox"/>		RESCIND <input type="checkbox"/>			
Foreign priority claimed <input type="checkbox"/> yes <input type="checkbox"/> no		35 USC 119 conditions met <input type="checkbox"/> yes <input type="checkbox"/> no		ATTORNEY DOCKET NO	
Verified and Acknowledged Examiners's initials				TI: 33887	
TITLE: Wafer level method for direct bumping on copper pads in integrated circuits					

NOTICE OF ALLOWANCE MAILED		Assistant Examiner Primary Examiner		DRAWING Sheets Drawn: [] [] [] Application Examiner	
ISSUE FEE Amount Due: [] Date Paid: []		PREPARED FOR ISSUE		WARNING: The information disclosed herein may be restricted. Unauthorized disclosure may be prohibited by the United States Code Title 35, Sections 122, 131 and 363. Possession outside the U.S. Patent & Trademark Office is restricted to authorized employees and contractors only.	

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